

L Number	Hits	Search Text	DB	Time stamp
3	0	"integrated particle monitor" with laser with reflect\$4	USPAT; US-PGPUB	2004/10/07 13:24
5	0	"integrated particle monitor" same laser same reflect\$4	EPO; JPO; DERWENT	2004/10/07 13:24
4	2	"integrated particle monitor" same laser same reflect\$4	USPAT; US-PGPUB	2004/10/07 13:25
6	25	"integrated particle monitor"	USPAT; US-PGPUB	2004/10/07 13:29
7	2	"integrated particle monitor" same laser	USPAT; US-PGPUB	2004/10/07 13:25
13	83	((monitor\$4 detect\$4 measur\$4 observ\$4) with (particle) with laser with reflect\$4) same (wafer substrate workpiece semiconductor)	USPAT; US-PGPUB	2004/10/07 13:31
14	24	((monitor\$4 detect\$4 measur\$4 observ\$4) with (particle) with laser with reflect\$4) same (wafer substrate workpiece semiconductor)	EPO; JPO; DERWENT	2004/10/07 14:17
15	1	("4669875").PN.	USPAT; US-PGPUB	2004/10/07 14:17
16	127	((transfer\$4 transport\$3) with chamber) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	2004/10/07 15:13
17	81	((transfer\$4 transport\$3) with chamber) same ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	2004/10/07 15:13
18	112	c23c016\$.ipc. and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	2004/10/07 15:14
19	45	verhaverbeke-steven.in. truman-j-kelly.in. lane-christopher-t.in.	USPAT; US-PGPUB	2004/10/07 15:15
20	4	(verhaverbeke-steven.in. truman-j-kelly.in. lane-christopher-t.in.) and (particle same monitor\$4)	USPAT; US-PGPUB	2004/10/07 15:15
-	208	(118/\$.ccls. 156/345\$.ccls.) and ((monitor\$3 determin\$3 measure\$3) with (particle particulate debris) with surface)	USPAT; US-PGPUB	2003/08/08 12:32
-	2550	(118/\$.ccls. 156/345\$.ccls.) and ((monitor\$3 determin\$3 measure\$3) with (thickness))	USPAT; US-PGPUB	2003/08/08 12:32
-	1414	(118/\$.ccls. 156/345\$.ccls.) and ((monitor\$3 measure\$3) with (thickness))	USPAT; US-PGPUB	2003/08/08 12:32
-	113	(118/\$.ccls. 156/345\$.ccls.) and ((monitor\$3 measure\$3) with (particle particulate debris) with surface)	USPAT; US-PGPUB	2003/08/08 13:09
-	9	5837094.URPN.	USPAT	2003/08/08 12:45
-	999	(monitor\$3 measure\$3 detect\$3) with (particle particulate debris) with surface with (wafer substrate semiconductor)	USPAT; US-PGPUB	2003/08/08 19:50
-	48978	c23c016\$.ipc.	EPO; JPO; DERWENT	2003/08/08 13:36
-	0	(monitor\$3 measure\$3 detect\$3) with (particle particulate debris) with surface with (wafer substrate semiconductor)	EPO; JPO; DERWENT	2003/08/08 13:11
-	0	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/08/08 13:32
-	1752	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/08/08 19:50
-	105	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 13:36
-	48978	c23c016\$.ipc.	EPO; JPO; DERWENT	2003/08/08 13:36
-	59	4693777.URPN.	USPAT	2003/08/08 13:55
-	103	c23c016\$.ipc. and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	2004/10/07 15:13
-	2	09/945,454	USPAT; US-PGPUB	2003/08/08 15:42

-	2	09/945454	USPAT; US-PGPUB	2003/08/08 15:42
-	121	((transfer\$4 transport\$3) with chamber) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	2004/10/07 15:13
-	2388	((transfer\$4 transport\$3) with chamber) and ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 15:54
-	122	((transfer\$4 transport\$3) with chamber) with ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 15:54
-	57	((transfer\$4 transport\$3) with chamber) with ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	2003/08/08 15:55
-	76	((transfer\$4 transport\$3) with chamber) same ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	EPO; JPO; DERWENT	2004/10/07 15:13
-	194	((transfer\$4 transport\$3) with chamber) same ((monitor\$3 detect\$3 measur\$4) with (particle particulate dust))	USPAT; US-PGPUB	2003/08/08 16:28
-	2	118/719.ccls. and imahashi.in.	USPAT; US-PGPUB	2003/08/08 17:01
-	1	("5909276").PN.	USPAT; US-PGPUB	2003/08/08 20:03
-	1752	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	USPAT; US-PGPUB	2003/08/08 19:59
-	11	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.) and (ash\$3 with atmospher\$3 with pressure)	USPAT; US-PGPUB	2003/08/08 19:57
-	324	ash\$3 with atmospher\$3 with pressure	USPAT; US-PGPUB	2003/08/08 19:57
-	139	ash\$3 with "atmospheric pressure"	USPAT; US-PGPUB	2003/08/08 19:57
-	76	ash\$3 with "atmospheric pressure"	EPO; JPO; DERWENT	2003/08/08 19:58
-	1	c23c016\$.ipc. and (ash\$3 with "atmospheric pressure")	EPO; JPO; DERWENT	2003/08/08 19:59
-	11	(chamber with ash\$3 with "atmospheric pressure")	EPO; JPO; DERWENT	2003/08/08 19:59
-	23	(ashing with "atmospheric pressure")	EPO; JPO; DERWENT	2003/08/08 20:00
-	2	"06177093"	EPO; JPO; DERWENT	2003/08/10 16:17